

TOREX SEMICONDUCTOR LTD.
Quality Assurance Dept.

Composition Table

Product(Pb-free): XC6210xxxxDR-G
Typical Mass: 6 mg

| Part name | Weight(mg) | Material name | Ratio(ppm) | CAS number |
|--------------|------------|---------------|------------|------------|
| Silicon chip | 0.727 | Silicon | 121200 | 7440-21-3 |
| | - | Arsenic | 6 | 7440-38-2 |
| Lead pad | 1.100 | Nickel | 183400 | 7440-02-0 |
| | 0.087 | Silver | 14600 | 7440-22-4 |
| | 0.016 | Gold | 2700 | 7440-57-5 |
| Die attach | 0.016 | Epoxy Resin | 2700 | — |
| | 0.012 | Silica | 2100 | 60676-86-0 |
| Bonding wire | 0.093 | Gold | 15400 | 7440-57-5 |
| | | | | |
| Resin | 3.553 | Silica | 592200 | 60676-86-0 |
| | 0.217 | Epoxy Resin | 36200 | — |
| | 0.178 | Phenol Resin | 29600 | — |
| | | | | |

* The component composition is based on the information provided by raw material vender.

* The mass of the IC and its fractions could be different due to the manufacturing conditions of materials.

* Any indication "-" in CAS number means "confidential."